

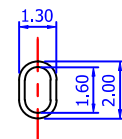
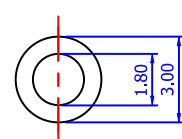
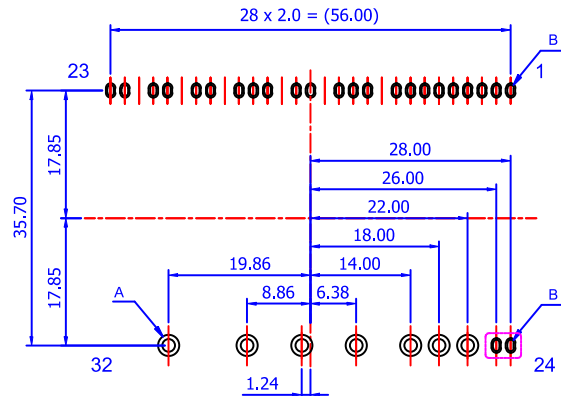
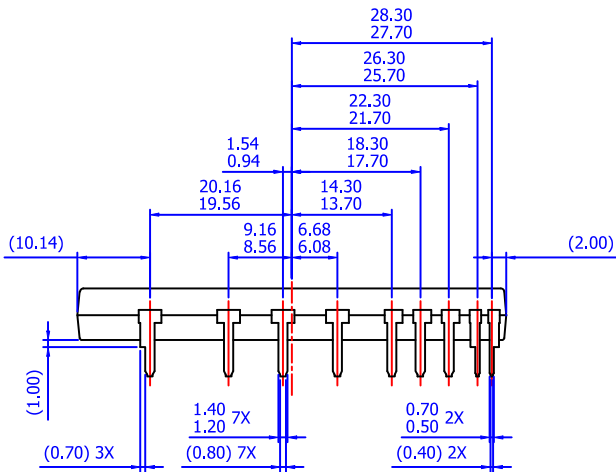
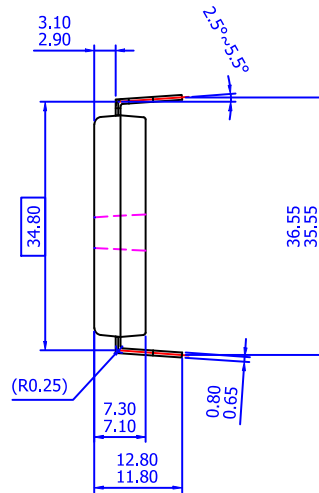
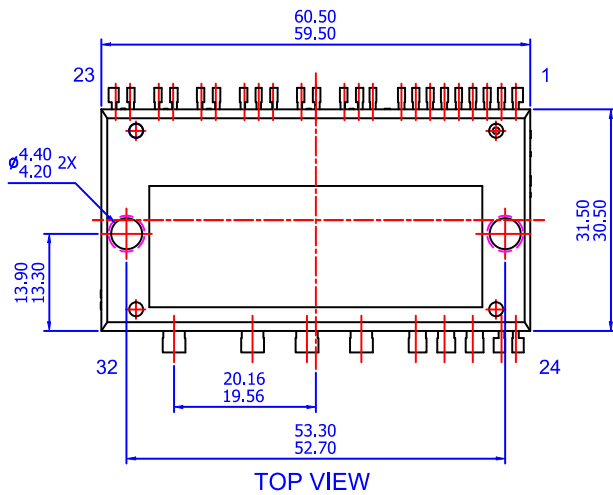
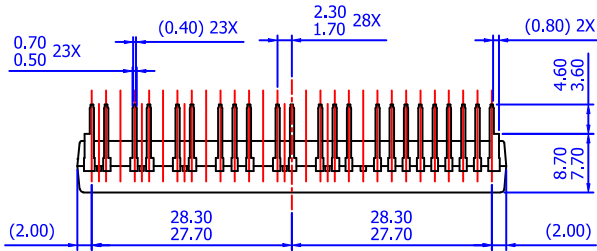
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



S32AA-032 / 32LD, PDD STD, CERAMIC DIP TYPE CASE MODDV ISSUE 0

DATE 31 DEC 2016



- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 D) () IS REFERENCE

LAND PATTERN RECOMMENDATIONS

DOCUMENT NUMBER:	98AON13534G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	S32AA-032 / 32LD, PDD STD, CERAMIC DIP TYPE	PAGE 1 OF 2

